

In the Claims:

Claims 1 - 20 (canceled).

Claim 21 (previously presented): An electronic package, comprising:

a substrate having at least two electrical contact pads thereon; and

a passive SMD having at least two electrical contacts each having at least a lower electrical contact surface and an upper electrical contact surface at the terminus thereof with at least said lower electrical contact surface of said at least two electrical contacts of said passive SMD respectively positioned toward said at least two electrical contact pads of said substrate and with said at least said lower electrical contact surface and said upper electrical contact surface at the terminus thereof of said at least two electrical contacts each respectively bonded by a solder connection to the said at least two electrical contact pads on said substrate such that said upper contact surface is covered by said solder connection, said passive SMD encapsulated by a resin such that the space between said passive SMD and said substrate is filled with said resin and with said resin further forming fillets around each said passive SMD solder connection including forming fillets covering said solder connection covering said upper contact surface.

Claim 22 - 24 (canceled)

Claim 25 (previously presented: An electronic package, comprising:

a substrate having at least two electrical contact pads thereon; and

a passive SMD having at least two electrical contacts each having at least a lower electrical contact surface and an upper electrical contact surface at the terminus thereof with at least said lower electrical contact surface of said at least two electrical contacts of said passive SMD respectively positioned toward said at least two electrical contact pads of said substrate and with said at least said lower electrical contact surface and said upper electrical contact surface at the terminus thereof of said at least two electrical contacts each respectively bonded by a solder connection to the said at least two electrical contact pads on said substrate such that said upper contact surface is covered by said solder connection, said passive SMD encapsulated by a resin formed from an epoxy-based flux encapsulant with flux combined into a one part epoxy system such that the space between said passive SMD and said substrate is filled with said resin and with said resin further forming fillets around each said passive SMD solder connection including forming fillets covering said solder connection covering said upper contact surface.